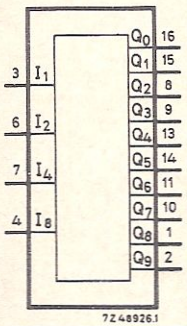
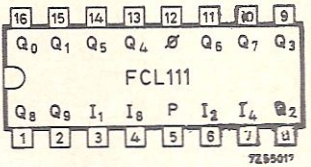
The FC family of DTL silicon monolithic integrated circuits has been designed for medium speed digital applications in computing, office electronics, telecommunication, instrumentation and industrial control.

development sample data

SINGLE DECODER/DRIVER FOR NUMERICAL INDICATOR TUBES





QUICK REFERENCE DATA				
Supply voltage	V_P		4.75 to 6.3	V
Operating ambient temperature range	T_{amb}		0 to +75	°C
Output voltage				
at I_{QL} = 20 mA	V_{QL}	max.	3	V
at I_{QH} = 20 μA to 2.2 mA	V_{QH}	min.	80	V
D.C. noise margin				
T_{amb} = 25 °C	M_L	typ.	1.2	V
Power consumption at T_{amb} = 25 °C	P_{av}	typ.	125	mW

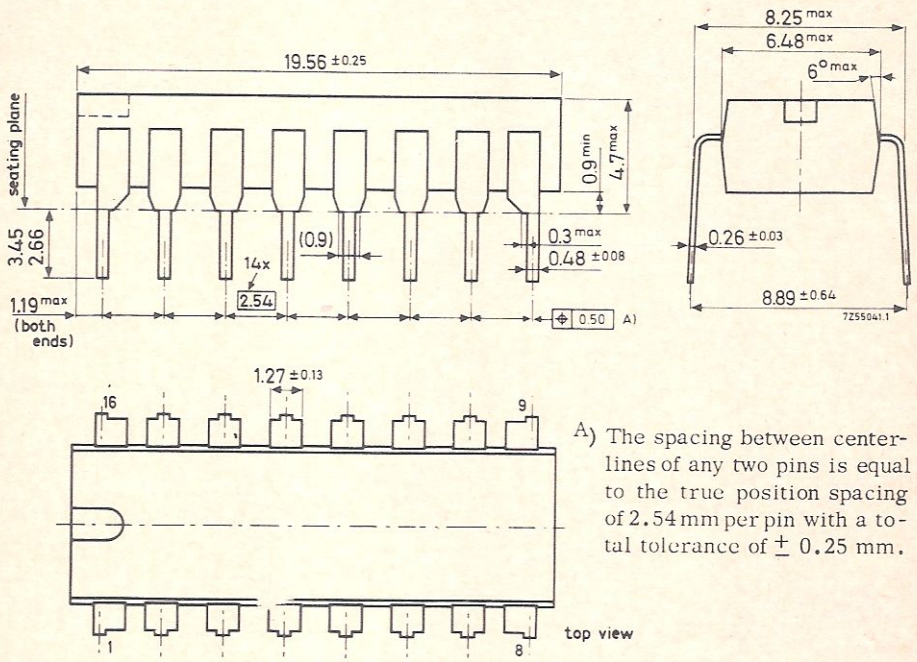
The FCL111 contains a decoding array for two codes, NBCD and EXCESS THREE, followed by ten output driver stages, which can be used for parallel or serial drive. For parallel drive no external clamping diodes are needed. For serial drive the cathode voltages must be clamped to prevent excessive dissipation, which may be caused by the leakage currents when the cathodes are cut-off.

These data, based on the specifications and measured performance of development samples, afford a preliminary indication of the characteristics to be expected of the described product. Distribution of development samples implies no guarantee as to the subsequent availability of the product

Red binder Integrated circuits

PACKAGE OUTLINE

Dimensions in mm



A) The spacing between centerlines of any two pins is equal to the true position spacing of 2.54 mm per pin with a total tolerance of ± 0.25 mm.

Handling notes

1. Devices may be soldered directly into circuits with soldering irons. At iron temperatures below 245 °C the maximum soldering time should be less than 10 seconds and at iron temperatures between 245 °C and 400 °C the soldering time should be less than 5 seconds. In both cases the soldering iron should be applied below the seating plane (see outline drawing).

2. Devices mounted up to the seating plane on a printed circuit board may be dip or flow soldered providing the solder temperature is below 245 °C and the time of immersion is less than 5 seconds. The body temperature should not be allowed to exceed the maximum storage temperature during soldering. If excessive preheat cycles are used, it may be necessary to cool the printed board immediately after leaving the solder bath/wave in order that this requirement is met.